

5-103166-3 ✓ ACTIVE

AMPMODU | AMPMODU Headers

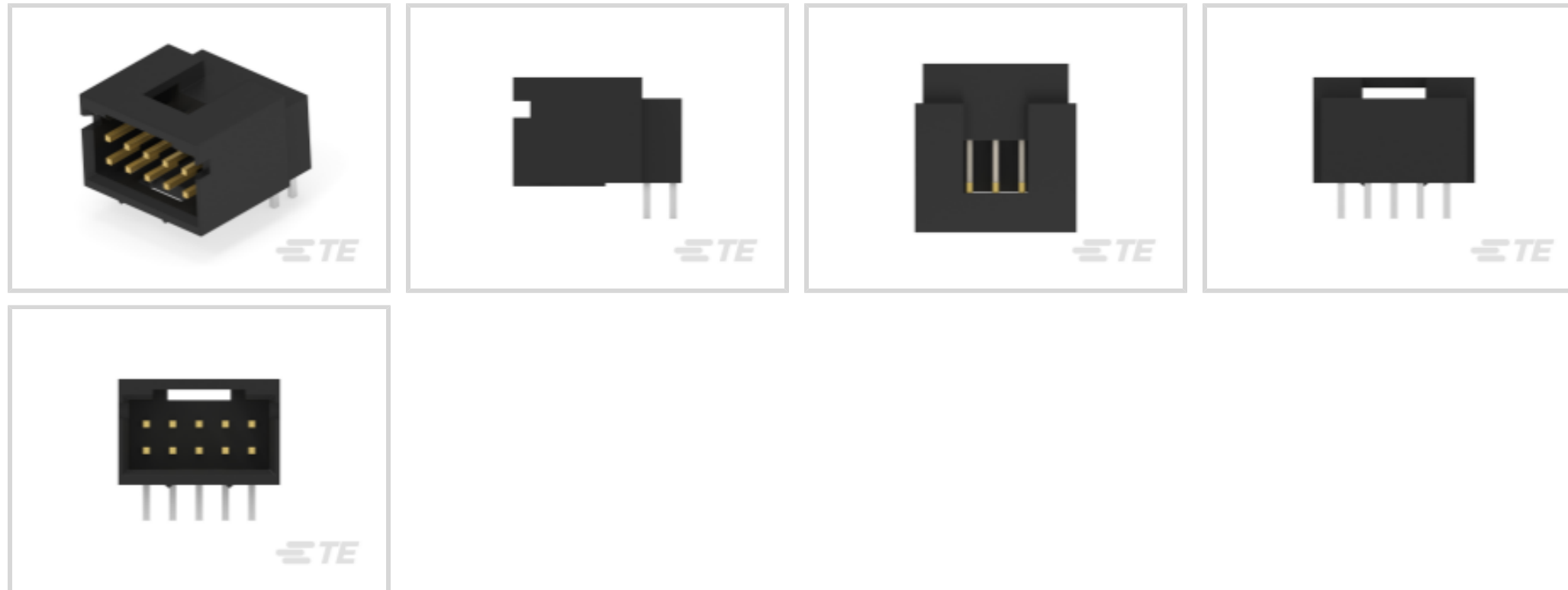
TE Internal #: 5-103166-3

PCB Mount Header, Right Angle, Board-to-Board / Wire-to-Board,
10 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold,
AMPMODU Headers

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Connectors > PCB Connectors > PCB Headers & Receptacles



EU RoHS Compliance: **Compliant**

EU ELV Compliance: **Compliant**

PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Right Angle**

Connector System: **Wire-to-Board, Board-to-Board**

Features

Other

EU RoHS Compliance **Compliant**

EU ELV Compliance **Compliant**

Product Type Features

PCB Connector Assembly Type **PCB Mount Header**

Connector System **Wire-to-Board, Board-to-Board**

Header Type **Fully Shrouded**

Connector & Contact Terminates To **Printed Circuit Board**

Configuration Features

Connector Contact Load Condition **Fully Loaded**

PCB Mount Orientation **Right Angle**

Number of Positions **10**

Number of Rows **2**

Electrical Characteristics

Insulation Resistance **5000 MΩ**



Dielectric Withstanding Voltage (Max)	750 Vrms
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Body Features

Connector Profile	Standard
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Primary Product Color	Black
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Contact Features

Contact Underplating Material	Nickel
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Contact Mating Area Plating Material Thickness	.762 μm[30 μin]
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Mating Square Post Dimension	.64 mm[.025 in]
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PCB Contact Termination Area Plating Material Thickness	2.54 – 5.08 μm[100 – 200 μin]
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Contact Shape & Form	Square
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Contact Base Material	Phosphor Bronze
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PCB Contact Termination Area Plating Material	Tin
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Contact Mating Area Plating Material	Gold
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Contact Type	Pin
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Contact Current Rating (Max)	3 A
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Termination Features

Termination Post & Tail Length	3.43 mm[.135 in]
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Square Termination Post & Tail Dimension	.64 mm[.025 in]
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Termination Method to PCB	Through Hole - Solder
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Mechanical Attachment

Mating Retention Type	Detent Window
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Mating Retention	With
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Mating Alignment Type	Polarization
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PCB Mount Retention	Without
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PCB Mount Alignment	Without
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Connector Mounting Type	Board Mount
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Mating Alignment	With
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Housing Features

Housing Material	Thermoplastic
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Centerline (Pitch)	2.54 mm[.1 in]
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Dimensions

Row-to-Row Spacing	2.54 mm[.1 in]
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PCB Thickness (Recommended)	1.4 mm[.055 in]
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Usage Conditions

Housing Temperature Rating	Standard
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]

Operation/Application

Solder Process Feature	Board Standoff
Circuit Application	Signal

Industry Standards

Compatible With Agency/Standards Products	CSA
Compatible With Approved Standards Products	UL E28476, CSA LR7189
UL Flammability Rating	UL 94V-0

Packaging Features

Packaging Quantity	2240
Packaging Method	Tray

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	BFR/CFR/PVC Free, but Br/Cl >900 ppm in other sources.
Solder Process Capability	Wave solder capable to 240°C

Product Compliance Disclaimer

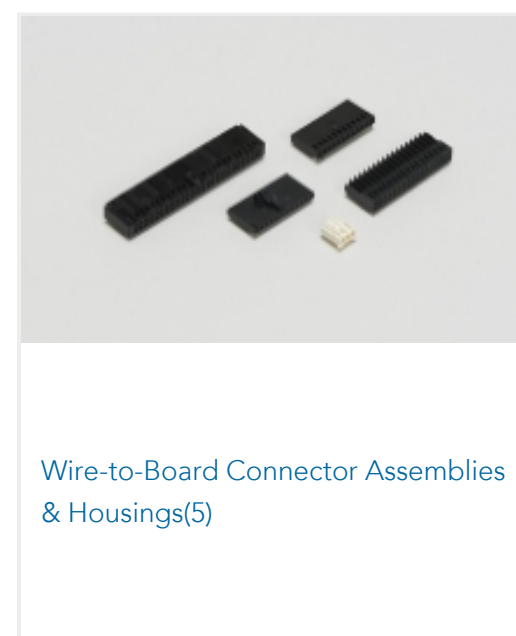
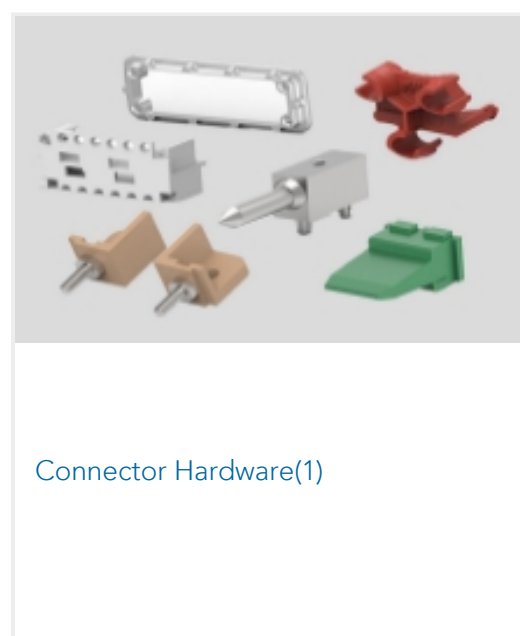
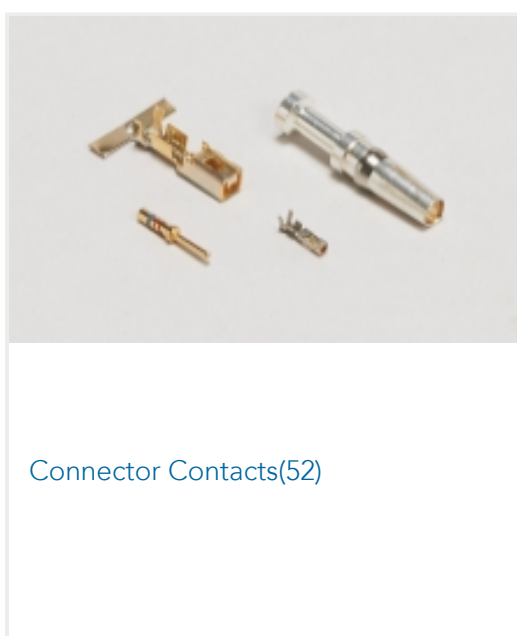
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides

on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

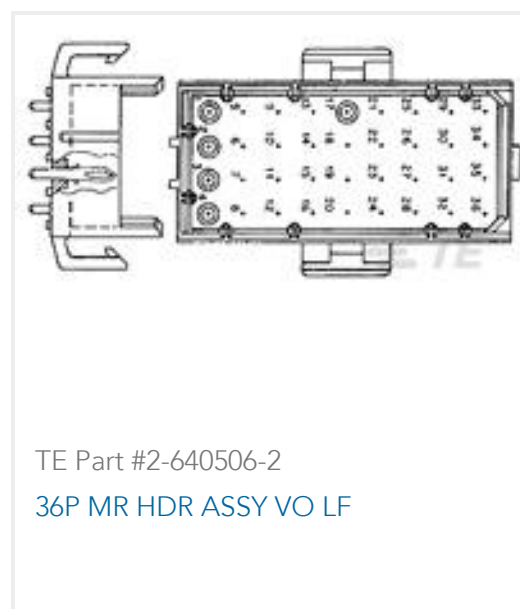
Compatible Parts



Also in the Series | AMPMODU Headers



Customers Also Bought



Documents

Product Drawings



10 MODII HDR DRRR SHRD LF

English

CAD Files

3D PDF

English

Customer View Model

[ENG_CVM_5-103166-3_K.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_5-103166-3_K.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_5-103166-3_K.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

[AMPMODU_INTERCONNECTION_SYSTEM_SECTION5](#)

English

[AMPMODU Interconnetion System](#)

[AMPMODU Interconnetion System](#)

English